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5 Modular System Profile

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Foreword

- 114 The Modular System Profile (DSP1008) was prepared by the Server Management Working Group and
- the Physical Platform Profiles Working Group of the DMTF.
- 116 DMTF is a not-for-profit association of industry members dedicated to promoting enterprise and systems
- 117 management and interoperability.
- 118

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Introduction

136 The information in this specification should be sufficient for a provider or consumer of this data to identify

137 unambiguously the classes, properties, methods, and values that shall be instantiated and manipulated to

138 represent and manage a blade system that is modeled using the DMTF CIM core and extended model 139 definitions.

140 The target audience for this specification is implementers who are writing CIM-based providers or

141 consumers of management interfaces that represent the component described in this document.

Modular System Profile

143 **1 Scope**

142

144 The Modular System Profile is an autonomous profile for modeling blade systems.

145 **2 Normative References**

- 146 The following referenced documents are indispensable for the application of this document. For dated 147 references, only the edition cited applies. For undated references, the latest edition of the referenced
- document (including any amendments) applies.

149 2.1 Approved References

150 DMTF DSP0004, CIM Infrastructure Specification 2.3,

- 178 DMTF DSP1024, Text Console Redirection Profile 1.0,
- 179 <u>http://www.dmtf.org/standards/published_documents/DSP1024_1.0.pdf</u>
- 180 DMTF DSP1025, Firmware Update Profile 1.0,
- 181 <u>http://www.dmtf.org/standards/published_documents/DSP1025_1.0.pdf</u>
- 182 DMTF DSP1027, Server Power State Management Profile 1.0,
- 183 <u>http://www.dmtf.org/standards/published_documents/DSP1027_1.0.pdf</u>
- 184 DMTF DSP1033, Profile Registration Profile 1.0,
 185 <u>http://www.dmtf.org/standards/published_documents/DSP1033_1.0.pdf</u>

186 2.2 Other References

187 ISO/IEC Directives, Part 2, *Rules for the structure and drafting of International Standards*,
 188 http://isotc.iso.org/livelink/livelink.exe?func=ll&objld=4230456&objAction=browse&sort=subtype

189 3 Terms and Definitions

	8	DMTF Standard	Version 1.0.0
215 216 217 218	3.8 referencing profile indicates a profile that owns the de "Referenced Profiles" table	finition of this class and can include a referen	ce to this profile in its
212 213 214	3.7 optional indicates a course of action permis	sible within the limits of the document	
209 210 211	3.6 need not indicates a course of action permis	sible within the limits of the document	
206 207 208	3.5 may indicates a course of action permis	sible within the limits of the document	
202 203 204 205	3.4 mandatory indicates requirements to be follow permitted	ed strictly to conform to the document and fro	om which no deviation is
198 199 200 201	3.3 conditional indicates requirements to be follow are met	ed strictly to conform to the document when t	he specified conditions
195 196 197	3.2 cannot used for statements of possibility a	nd capability, whether material, physical, or ca	ausal
192 193 194	3.1 can used for statements of possibility a	nd capability, whether material, physical, or ca	ausal
190 191	For the purposes of this document, apply.	the terms and definitions in <u>DSP1033</u> and <u>D</u>	SP1001 and the following

219 **3.9**

- 220 shall
- indicates requirements to be followed strictly to conform to the document and from which no deviation is permitted

223 **3.10**

shall not

- indicates requirements strictly to be followed in order to conform to the document and from which no
- 226 deviation is permitted

227 **3.11**

- 228 should
- indicates that among several possibilities, one is recommended as particularly suitable, without
- 230 mentioning or excluding others, or that a certain course of action is preferred but not necessarily required

231 **3.12**

232 should not

233 indicates that a certain possibility or course of action is deprecated but not prohibited

234 **3.13**

235 unspecified

236 indicates that this profile does not define any constraints for the referenced CIM element or operation

237 **3.14**

238 blade

- a physical package that contains one or more operational aspects of a datacenter such as storage,
- network, or computational functionality, while relying on the containing modular system for infrastructure
 such as power and cooling

242 **3.15**

243 blade expansion

- a physical package that provides additional operational aspects of a computer system to a blade, yet
- 245 contains insufficient functionality to support an operating system on its own
- 246 **3.16**

247 cooling domain

the set of systems and components that share a given cooling source that consists of one or more coolingdevices

250 **3.17**

251 modular enclosure

the physical packaging of a modular system

253 **3.18**

254 power domain

- the set of systems and components that receive power from a given power source that consists of one or more power supplies
- 257 **3.19**

258 processor blade

- a specific type of blade designed to provide processing capability in support of an operating system
- 260 **3.20**

261 storage blade

262 a specific type of blade designed to provide storage media or access

263 **4 Symbols and Abbreviated Terms**

264 None.

265 **5 Synopsis**

- 266 Profile Name: Modular System
- 267 Version: 1.0.0
- 268 **Organization:** DMTF
- 269 CIM Schema Version: 2.18
- 270 Central Class: CIM_ComputerSystem
- 271 Scoping Class: CIM_ComputerSystem

272 The *Modular System Profile* extends management capability to include support for blade architectures.

273 The Central Class of the *Modular System Profile* shall be CIM_ComputerSystem. The Central Instance of

the *Modular System Profile* shall be the instance of CIM_ComputerSystem that represents the modular

system. The Scoping Class for the *Modular System Profile* shall be CIM_ComputerSystem. The Scoping

- 276 Instance for the *Modular System Profile* shall be the Central Instance.
- 277

Table 1 – Referenced Profiles

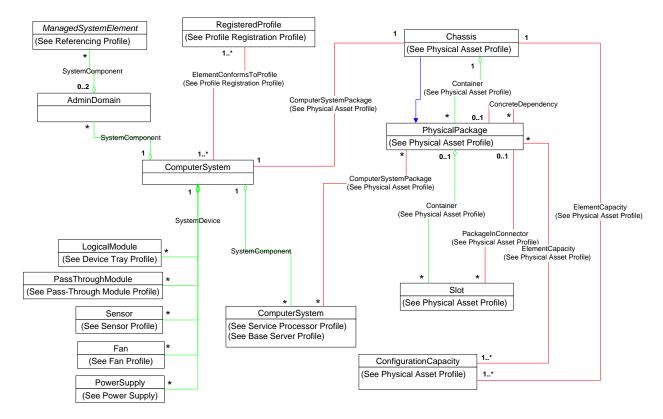
Profile Name	Organization	Version	Relationship	Description
Base Server	DMTF	1.0	Optional	See section 7.3.
Service Processor	DMTF	1.0	Optional	See section 7.4.
Device Tray	DMTF	DMTF 1.0 Optional See section 7.9.		See section 7.9.
<u>Fan</u>	DMTF	1.0	Optional	See section 7.7.
Pass-Through Module	DMTF	1.0	Optional	See section 7.10.
Physical Asset	DMTF	1.0	Mandatory	See section 7.2.
Power Supply	DMTF	1.0	Optional	See section 7.5.
Profile Registration	DMTF	1.0	Mandatory	None.
<u>Sensors</u>	DMTF	1.0	Optional	See section 7.11.

278 6 Description

The *Modular System Profile* describes blade systems. Its scope is limited to defining those classes or behaviors that are unique to blade systems. This profile includes support for the following functionality:

- representing modular systems, including topology
- representing the physical packaging of modular systems, including topology
- modeling power domains of modular systems
- modeling cooling domains of modular systems

Figure 1 represents the class schema for the *Modular System Profile*. For simplicity, the prefix CIM_ has been removed from the names of the classes.



287

288

Figure 1 – Modular System Profile: Class Diagram

289 **7 Implementation**

- This section details the requirements related to the arrangement of instances and their properties for implementations of the *Modular System Profile*.
- The list of all required extrinsic methods and intrinsic operations can be found in section 8 and properties in section 10.

7.1 Representing the Modular System

The modular system shall be modeled with an instance of CIM_ComputerSystem. It is possible that the only logical element instrumented will be the Central Instance when no modular components are installed in the modular system.

298 **7.1.1 Modular Enclosure**

A System Chassis, as defined in the <u>Physical Asset Profile</u>, shall represent the modular enclosure. An
 instance of CIM_ComputerSystemPackage shall reference the CIM_Chassis instance and the Central
 Instance.

302 **7.1.2 Scoping a Logical Device**

303 When the implementation uses CIM_LogicalDevice to model a device that is installed into the modular 304 enclosure and provides function to other components installed in the enclosure, the CIM_LogicalDevice

- instance shall be associated with the CIM_ComputerSystem instance that represents the modular
 enclosure through an instance of CIM_SystemDevice.
- 307 When the instrumentation uses CIM_LogicalDevice to model a component that is part of a chassis
- manager or processor blade, the CIM_LogicalDevice instance shall be associated with the instance of
 CIM_ComputerSystem that represents the chassis manager or processor blade through an instance of
 CIM SystemDevice.
- 311 When the instrumentation models a multi-component device that aggregates other devices in the modular 312 enclosure, the multi-component device shall be modeled with an instance of CIM_LogicalModule.

313 7.2 Physical Model

- This section details the requirements for modeling physical aspects of the modular system. The instrumentation shall be conformant with the <u>Physical Asset Profile</u>.
- 316 One or more instances of CIM_ConfigurationCapacity shall model the capacity of the modular system to 317 contain modular components.
- 318 An instance of CIM_Slot should exist for each slot or bay of the modular enclosure.

319 **7.3 Processor Blades**

The instrumentation of a processor blade shall be conformant with the <u>Base Server Profile</u>. An instance of CIM_SystemComponent shall exist in which the GroupComponent reference is to the Central Instance of this profile and the PartComponent reference is to the Central Instance of the <u>Base Server Profile</u>.

- 323 **7.3.1 Blade and Blade Expansion Packaging**
- Implementations shall create at least one instance of CIM_PhysicalPackage for each processor blade
 installed in the modular chassis. The existence of CIM_PhysicalPackage is conditional on the
 instrumentation of a CIM_ComputerSystem instance for a processor blade.

327 7.3.1.1 Blade Physical Package

Implementations shall assign a value of 16 (Blade) to the PackageType property of an instance of
 CIM_PhysicalPackage when the instance is being used to model a module that can be inserted into a
 modular chassis and host an operating system.

331 **7.3.1.2 Blade Expansion Physical Package**

Implementations shall assign a value of 17 (BladeExpansion) to the PackageType property of an instance of CIM_PhysicalPackage when the instance is being used to model a module that is not stand-alone, is attached to a "Blade" module prior to inserting both modules into the modular chassis, and is an external expansion of the "Blade" module.

336 **7.3.1.3** Relationship between Physical Packages and Slots

When a CIM_PhysicalPackage instance is created to represent a blade module installed in the chassis,
 the CIM_PhysicalPackage instance should be associated with one instance of CIM_Slot through the
 CIM_PackageInConnector association. Implementations may associate the CIM_PhysicalPackage
 instance with more than one instance of CIM_Slot.

341 **7.3.1.4** Relationship between Blade and Blade Expansion

342 If a CIM_PhysicalPackage instance is created to represent a blade expansion module and the module is

343 connected to a blade module, the implementation shall associate the CIM_PhysicalPackage that

represents the blade expansion to the CIM_PhysicalPackage that represents the blade through an

- instance of CIM_ConcreteDependency. The existence of an instance of CIM_ConcreteDependency is
- 346 conditional on the existence of an instance of CIM_PhysicalPackage to model a blade expansion.

347 **7.4 Service Processor Profile (Optional)**

A modular system may contain one or more chassis managers. When the instrumentation includes
 support for chassis managers, the chassis managers shall be instrumented compliant with the <u>Service</u>
 Processor Profile.

351 Each instance of CIM_ComputerSystem that represents a chassis manager shall be associated to the

- 352 Central Instance through the CIM_SystemComponent association. The GroupComponent property shall
- be a reference to the Central Instance. The PartComponent property shall be a reference to the
- 354 CIM_ComputerSystem instance that represents the chassis manager.

355 **7.5 Power Supply Profile (Optional)**

When an implementation instruments CIM_PowerSupply to model a power supply in the blade system,
 the instrumentation shall conform to the *Power Supply Profile*. When the optional behavior specified in
 section 7.6 is implemented, for all instances of CIM_SuppliesPower the Dependent reference shall be an

359 instance of CIM_AdminDomain.

360 **7.6 Power Domains (Optional)**

A modular system may be responsible for providing power to the modular components installed in it. When a modular system supplies power to modular components, the components may be members of one or more power domains. The power domains of the modular system should be modeled. When the power domains of a modular system are modeled, the requirements detailed in the following subclauses shall be met.

366 **7.6.1 Representing a Power Domain**

Exactly one instance of CIM_AdminDomain shall exist for each power domain in the modular system. The instance of CIM_AdminDomain shall be associated with the Central Instance through an instance of

369 CIM_SystemComponent, where the value of the GroupComponent property is the Central Instance and

370 the value of the PartComponent property is the CIM_AdminDomain instance.

371 **7.6.2 Power Supplies in Domain**

Each power supply that provides power to the power domain shall be associated with the

373 CIM_AdminDomain instance through an instance of CIM_SuppliesPower. When more than one power

supply is able to supply power to the domain, the optional behavior in the "Modeling Power Supply
 Redundancy" section of the *Base Server Profile* should be supported.

375 Redundancy" section of the <u>Base Server Profile</u> should be supported

376 **7.6.3 Representing Components in a Power Domain**

A component is considered to be in a power domain if it receives power from a power supply in the

domain. Each instance of a subclass of CIM_LogicalElement that represents a component in a power

domain shall be associated with the CIM_AdminDomain instance that represents the domain through the CIM SystemComponent association. The Central Instance may be associated with the

500 CIM_SystemComponent association. The Central Instance may be associated with the

381 CIM_AdminDomain instance through the CIM_SystemComponent, where the Central Instance is the 382 PartComponent reference. This indicates that components within the modular enclosure that are not

explicitly modeled receive power from the domain represented by the CIM_AdminDomain instance.

384 **7.6.4 Representing Slots in a Power Domain**

The slots or bays of the modular enclosure that are within a particular power domain may be modeled. A slot or bay is considered to be within a power domain if a component installed in the slot would receive

- power from the power supply or supplies for the domain. Each instance of CIM_Slot that represents a slot
- that is in a power domain shall be associated with the CIM_AdminDomain that represents the power
 domain through the CIM_SystemComponent association.

390 **7.7 Fan Profile (Optional)**

391 If an implementation instruments CIM_Fan to model the cooling functionality of a blade system, the

- implementation shall conform to the *Fan Profile*. When the optional behavior specified in section 7.8 is
 implemented, for each instance of CIM_AssociatedCooling the Dependent reference shall be an instance
- 394 of CIM_AdminDomain.

395 **7.8 Cooling Domains (Optional)**

A modular system may be responsible for providing cooling to the modular components installed in it. When a modular system supplies cooling to modular components, the components may be members of one or more cooling domains. The cooling domains of the modular system should be modeled. When the cooling domains of a modular system are modeled, the requirements detailed in the following subclauses shall be met.

401 **7.8.1 Representing a Cooling Domain**

402 Exactly one instance of CIM_AdminDomain shall exist for each cooling domain in the modular system.

403 The instance of CIM_AdminDomain shall be associated with the Central Instance through the

404 CIM_SystemComponent association, where the value of the GroupComponent property is the Central

Instance and the value of the PartComponent property is the CIM_AdminDomain instance.

406 **7.8.2 Fans in Domain**

407 Each instance of CIM_Fan that represents a fan that provides cooling to the cooling domain shall be

associated with the CIM_AdminDomain instance through the CIM_AssociatedCooling association. When
 more than one fan is able to supply cooling to the domain, the optional behavior in the "Modeling Fan
 Redundancy" section of the *Fan Profile* should be supported.

411 **7.8.3** Representing Components in a Cooling Domain

412 A component is considered to be in a cooling domain if it receives cooling from a fan in the domain. Each 413 instance of a subclass of CIM_LogicalElement that represents a component in a cooling domain shall be

- 414 associated with the CIM AdminDomain instance that represents the domain through the
- 415 CIM SystemComponent association. The Central Instance may be associated with the
- 416 CIM_AdminDomain instance through the CIM_SystemComponent association, where the value of the
- 417 PartComponent property is the Central Instance. This indicates that components within the modular
- 418 enclosure that are not explicitly modeled receive cooling from the domain represented by the
- 419 CIM_AdminDomain instance.

420 **7.8.4 Representing Slots in a Cooling Domain**

The slots or bays of the modular enclosure that are within a particular cooling domain may be modeled. A slot or bay is considered to be within a cooling domain if a component installed in the slot would receive

423 cooling from the fan or supplies for the domain. Each instance of CIM_Slot that represents a slot that is in

- 424 a cooling domain shall be associated with the instance of CIM_AdminDomain that represents the cooling
- domain through the CIM_SystemComponent association.

426 **7.9 Device Tray Profile (Optional)**

427 A modular system may include one or more device trays. When a device tray is modeled, the 428 instrumentation shall be conformant with the *Device Tray Profile*.

429 **7.10 Pass-Through Module Profile (Optional)**

430 A modular system may include one or more pass-through modules. When a pass-through module is

modeled, the instrumentation shall be in accordance with the requirements specified in the <u>Pass-Through</u>
 <u>Module Profile</u>.

433 **7.11 Sensor Profile (Optional)**

If the instrumentation includes support for modeling sensors, the instrumentation shall be conformant with
 the <u>Sensors Profile</u>.

436 **7.11.1 Component Presence Sensors**

Presence sensors used to determine whether components are installed in slots in the modular system
may be modeled using CIM_Sensor. When an instance of CIM_Sensor is used to model a presence
sensor for a slot, the CIM_Sensor.SensorType property shall have the value 11 (Presence) and shall be
associated with the CIM_Slot instance through the CIM_AssociatedSensor association.

441 8 Methods

This section details the requirements for supporting intrinsic operations for the CIM elements defined by this profile. No extrinsic methods exist for the CIM elements specified by this profile.

444 **8.1 Profile Conventions for Operations**

For each profile class (including associations), the implementation requirements for operations, including those in the following default list, are specified in class-specific subclauses of this clause.

- 447 The default list of operations is as follows:
- GetInstance
- Associators
- 450 AssociatorNames
- 451 References
- ReferenceNames
- EnumerateInstances
- EnumerateInstanceNames

455 8.2 CIM_AdminDomain

- 456 All operations in the default list in 8.1 shall be implemented as defined in <u>DSP0200</u>.
- 457 NOTE: Related profiles may define additional requirements on operations for the profile class.

458 8.3 CIM_ComputerSystem

- 459 All operations in the default list in 8.1 shall be implemented as defined in <u>DSP0200</u>.
- 460 NOTE: Related profiles may define additional requirements on operations for the profile class.

461 **8.4 CIM_ConcreteDependency**

Table 2 lists implementation requirements for operations. If implemented, these operations shall be implemented as defined in DSP0200. In addition, and unless otherwise stated in Table 2, all operations in

464 the default list in 8.1 shall be implemented as defined in DSP0200.

465 NOTE: Related profiles may define additional requirements on operations for the profile class.

466

Table 2 – Operations: CIM_ConcreteDependency

Operation	Requirement	Messages
Associators	Unspecified	None
AssociatorNames	Unspecified	None
References	Unspecified	None
ReferenceNames	Unspecified	None

467 **8.5 CIM_SystemComponent**

Table 3 lists implementation requirements for operations. If implemented, these operations shall be implemented as defined in <u>DSP0200</u>. In addition, and unless otherwise stated in Table 3, all operations in

470 the default list in 8.1 shall be implemented as defined in <u>DSP0200</u>.

471 NOTE: Related profiles may define additional requirements on operations for the profile class.

472

Table 3 – Operations: Cl	M_SystemComponent
--------------------------	-------------------

Operation	Requirement	Messages
Associators	Unspecified	None
AssociatorNames	Unspecified	None
References	Unspecified	None
ReferenceNames	Unspecified	None

473 9 Use Cases

This section outlines the use cases specific to modular systems. Use cases for functionality that is not specific to modular systems are documented in the profiles for that functionality. Use cases are

476 informative and are not intended to define the requirements for conformance.

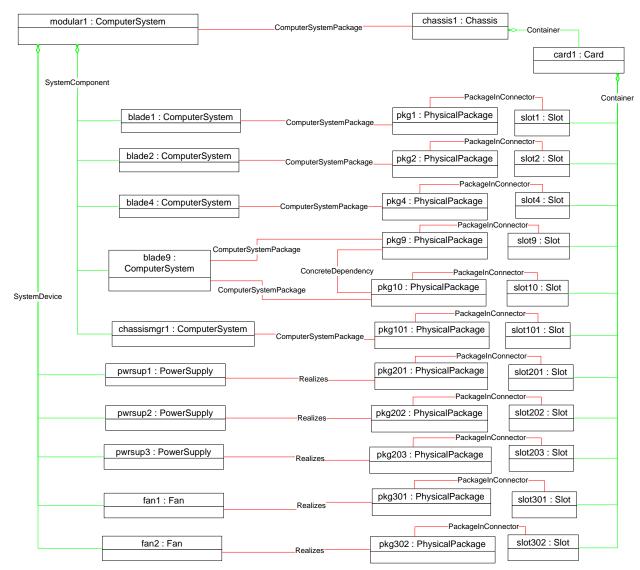
477 9.1 Object Diagrams

Figure 2 through Figure 7 are object diagrams that represent a possible instantiation of the *Modular* System Profile.

Figure 2 shows the high-level topology of a modular system. The following components are currently installed in the enclosure:

- 482 four blade servers
- three power supplies
- two fans
- 485 one chassis manager

486 Blade servers blade1, blade2, and blade4 each consist of a single package installed in a single slot in the 487 enclosure. blade9 consists of two packages and occupies two slots in the enclosure.



488

489

Figure 2 – Logical and Physical Topology

Figure 3 shows the capacity and compatibility of the modular enclosure. Each type of slot is identified with

a unique value for the VendorCompatibilityStrings property of an instance of CIM_Slot, which

492 corresponds to the value of the VendorCompatibilityStrings property of one of the instances of

493 CIM_ConfigurationCapacity. For example, the VendorCompatibilityStrings properties of slot1 and cap1

494 have identical values. Note that an instance of CIM_Slot is not shown in the object diagram for each

495 possible slot as indicated by the MaximumCapacity property of the instances of

496 CIM_ConfigurationCapacity. The corresponding instances of CIM_Slot actually exist in the

instrumentation; however, they are not shown to reduce clutter in the diagram. As indicated in Figure 2,

498 blade9 consists of two packages and occupies two slots in the enclosure. pkg10 is a BladeExpansion

499 (PackageType = 17) attached to pkg9 (PackageType = 16). An instance of CIM_ConcreteDependency
 500 associates the two instances.

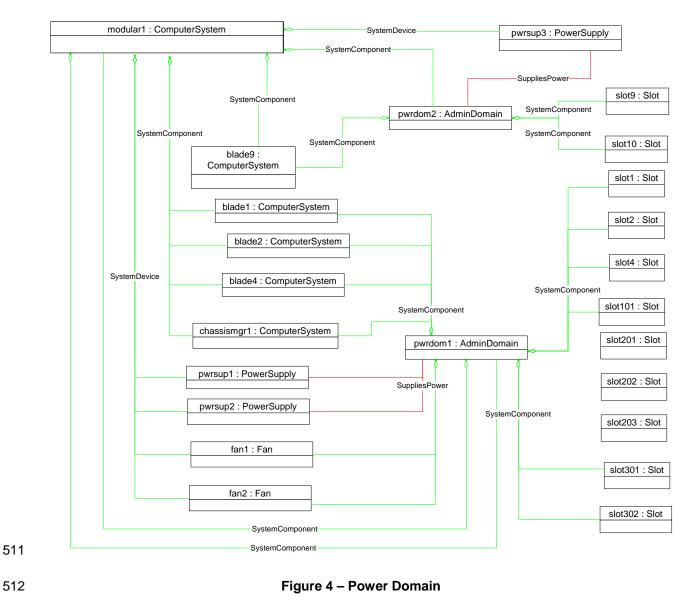
			-	. Г	chassis1 : Chassis	
			Con	tainer-		
		ca	rd1 : Card			ElementCapacit
				_	cap1 : ConfigurationCapacity	-
pkg1 : PhysicalPackage	Γ	slot1 : Slot		Container	VendorCompatibilityStrings : "abc:bladeenclosure:processorblade"	
VendorCompatibilityStrings : "abc:bladeenclosure:processorblade:type20" PackageType : 16 (Blade)		VendorCompatibilityStrings : 'abc:bladeenclosure:processorbla	ade"		MaximumCapacity : 14 MinimumCapacity : 0 ObjectType : 0 (Other)	
pkg2 : PhysicalPackage		slot2 : Slot			cap2 : ConfigurationCapacity	
VendorCompatibilityStrings : "abc:bladeenclosure:processorblade:type20" PackageType : 16 (Blade)	PackageInConnector—	VendorCompatibilityStrings : "abc:bladeenclosure:processort	blade"	_	VendorCompatibilityStrings : "abc:bladeenclosure:management" MaximumCapacity : 2 MinimumCapacity : 1	
pkg4 : PhysicalPackage		slot4 : Slot			ObjectType : 0 (Other)	
VendorCompatibilityStrings : "abc:bladeenclosure:processorblade:type20" PackageType : 16 (Blade)	PackageInConnector—	VendorCompatibilityStrings : "abc:bladeenclosure:processort	blade"		cap3 : ConfigurationCapacity VendorCompatibilityStrings :	
pkg9 : PhysicalPackage					"abc:bladeenclosure:power" MaximumCapacity : 4	
VendorCompatibilityStrings : "abc:bladeenclosure:processorblade:type20" PackageType : 16 (Blade)	PackageInConnector-	slot9 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:processor	blade"		MinimumCapacity : 1 ObjectType : 2 (Power Supplies)	1
pkg10 : PhysicalPackage	1	slot10 : Slot			cap4 : ConfigurationCapacity VendorCompatibilityStrings :	
PNGTO: FTYSICalFackage VendorCompatibilityStrings : "abc:bladeenclosure:processorblade:TypeBSE" PackageType : 17 (Blade Expansion)	- PackageInConnector-	VendorCompatibilityStrings : "abc:bladeenclosure:processor	blade"		"abc:bladeenclosure:cooling" MaximumCapacity : 2 MinimumCapacity : 1 ObjectType : 3 (Fans)	
pkg101 : PhysicalPackage	_	slot101 : Slot				
VendorCompatibilityStrings : "abc:bladeenclosure:Management:mm1" PackageType : 9 (Module/Card)	PackageInConnector	VendorCompatibilityStrings : "abc:bladeenclosure:Managen	nent"			
pkg201 : PhysicalPackage]					
VendorCompatibilityStrings : "abc:bladeenclosure:power:power1400" PackageType : 6 (Power Supply)	PackageInConnector	slot201 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:power"				
pkg202 : PhysicalPackage		[
VendorCompatibilityStrings : "abc:bladeenclosure:power:power1400" PackageType : 6 (Power Supply)	PackageInConnector	slot202 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:power"				
pkg203 : PhysicalPackage						
VendorCompatibilityStrings : "abc:bladeenclosure:power:power1400" PackageType : 6 (Power Supply)	PackageInConnector-	slot203 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:power"				
pkg301 : PhysicalPackage						
VendorCompatibilityStrings : "abc:bladeenclosure:cooling:blower1" PackageType : 7 (Fan)	PackageInConnector	slot301 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:cooling"		_		
pkg302 : PhysicalPackage			_			
VendorCompatibilityStrings : "abc:bladeenclosure:ccoling:blower1" PackageType : 7 (Fan)	PackageInConnector-	slot302 : Slot VendorCompatibilityStrings : "abc:bladeenclosure:cooling"				

502

Figure 3 – Chassis Capacity and Compatibility

503 Figure 4 illustrates the modeling of power domains in the modular system. Two power domains are modeled, pwrdom1 and pwrdom2. Components in pwrdom1 receive power from power supplies pwrsup1 504 and pwrsup2, which is indicated by the instances of CIM_SuppliesPower that associate pwrsup1 and 505 pwrsup2 with pwrdom1. Components in pwrdom2 receive power from pwrsup3. Slots that can hold power 506 supplies are not associated with any power domain. The CIM Slot instances for slots that receive power 507 508 from the supplies in the domain are always associated with the CIM_AdminDomain instance for the 509 domain through the CIM_SystemComponent association, even when a component has been installed in 510 the slot and is itself associated with the domain.

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- 513 Figure 5 illustrates power management of the modular system and installed blades that are available
- 514 through the installed chassis manager. The modular system and installed blades are all receiving trickle
- 515 (flea) power as indicated by the value of the PowerState property for each of the instances of
- 516 CIM_AssociatedPowerManagementService. The power management functionality supplied by the
- 517 chassis manager is the same for the installed processor blades but distinct for the modular system itself.
- 518 Thus, two instances of CIM_PowerManagementService exist, with associated instances of
- 519 CIM_PowerManagementCapabilities indicating the functionality available.

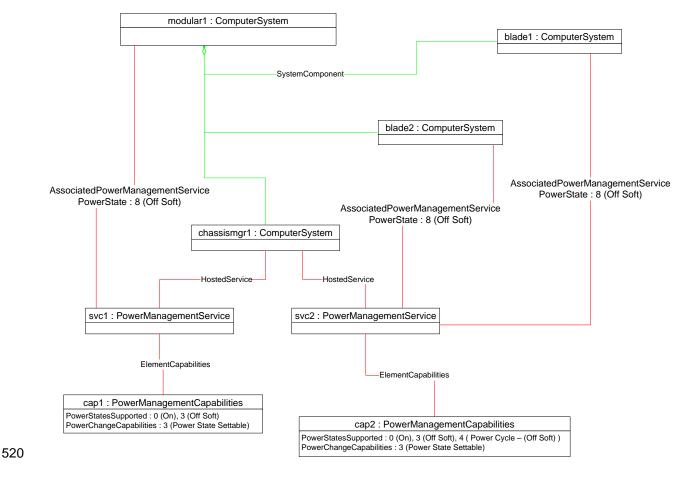


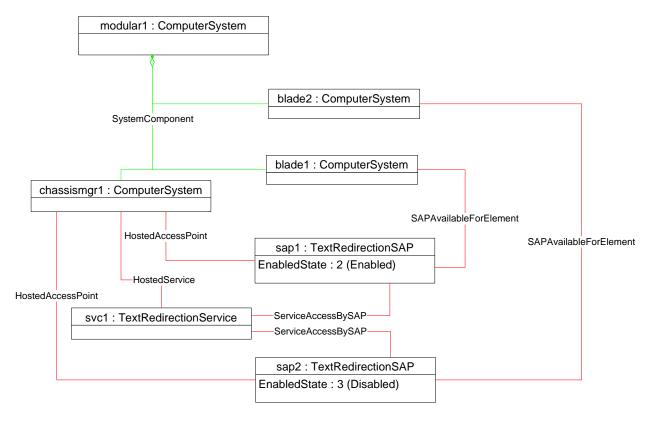
Figure 5 – Power Management Hosted on Chassis Manager

522 Figure 6 represents the ability of the chassis manager to provide text redirection for the processor blades.

523 The availability of the function from the chassis manager is indicated by the CIM_HostedService 524 association between svc1 and chassismgr1. The availability of the function to the processor blades is

indicated by the instances of CIM_SAPAvailableForElement that associate sap1 and sap2 to blade1 and

526 blade2, respectively.



528

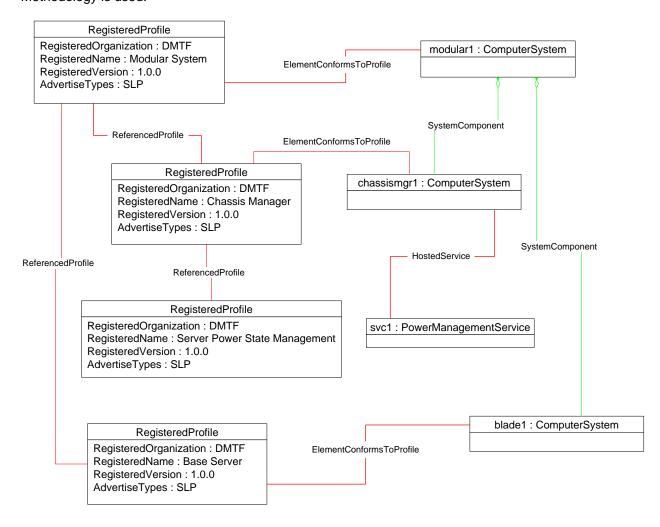
Figure 6 – Text Console Redirection Hosted on Chassis Manager

529 Figure 7 indicates how an implementation would advertise the implementation of the Modular System

530 *Profile*. The instances of CIM_RegisteredProfile are created in the Interop namespace while the other

instances are created in an Implementation namespace. The *Modular System Profile* and the <u>Service</u>
 Processor Profile are autonomous profiles. Thus the Central Class Methodology is used. The <u>Server</u>

- 532 <u>Processor Profile</u> are autonomous profiles. Thus the Central Class Methodology is used. The <u>Serve</u> 533 <u>Power State Management Profile</u> is a component profile, and, in this instance, the Scoping Class
- 534 Methodology is used.



536

535

Figure 7 – Registered Profile

9.2 Find the CIM_ComputerSystem Instance for the Enclosure

- 538 A client can determine whether a modular enclosure is modeled as follows:
- Look in the Interop namespace for an instance of CIM_RegisteredProfile that represents this
 profile specification.
- 541 2) Look for instances of the CIM_ElementConformsToProfile association that reference the 542 CIM_RegisteredProfile instance.
- 5433)Find the CIM_ComputerSystem instance that represents the modular enclosure by traversing544each instance of the CIM_ElementConformsToProfile association to an instance of545CIM_ComputerSystem. These referenced CIM_ComputerSystem instances model modular546enclosures.

547 9.3 Query Chassis Capacity

- 548 Clients can determine the capacity of the chassis for components of a particular type as follows:
- 549 1) Starting at the CIM_ComputerSystem instance that represents the modular enclosure as found
 550 in section 9.2, traverse the CIM_ComputerSystemPackage association to the instance of
 551 CIM_Chassis that is the physical side of the model for the modular enclosure.
- 552 2) Use the CIM_ElementCapacity association to find each instance of CIM_ConfigurationCapacity 553 that is associated with the CIM_Chassis instance.
- 5543)Query the ObjectType and VendorCompatibilityStrings properties of each555CIM_ConfigurationCapacity instance to find the instance that represents the component type of556interest.
- 4) Query the MinimumCapacity and MaximumCapacity properties to determine the capacity of the enclosure for the component type.

559 9.4 Query Chassis Component Presence

- 560 A client can determine which components are currently installed in the chassis as follows:
- 561 1) Find the CIM_ComputerSystem instance that represents the modular enclosure as specified in section 9.2.
- 563 2) Find all instances of the CIM_SystemComponent association (or subclass) that reference the 564 CIM_ComputerSystem instance, where a reference to the CIM_ComputerSystem instance is 565 the value of the GroupComponent.
- 566 3) Traverse each association instance to the referenced CIM_ManagedSystemElement. The 567 referenced CIM_ManagedSystemElement represents a component installed in the enclosure.
- For components that have a corresponding physical presence, if the implementation has
 instrumented the physical side of the model, find instances of the CIM_Realizes association that
 reference the CIM_ManagedSystemElement instance.
- 571 5) Traverse the instance of CIM_Realizes to the CIM_PhysicalPackage (or subclass) instance.
- 572 6) If an instance of CIM_PackageInConnector (or subclass) references this instance, determine 573 the slot or connector in which the component is installed.
- 574 9.5 Query Chassis Manager Presence
- 575 A client can determine if a Chassis Manager is installed as follows:
- 576 1) Find the CIM_ComputerSystem instance that represents the modular enclosure as described in 577 section 9.2.
- Use the steps described in section 9.4 to determine which components are installed in the
 enclosure, and look for an instance of CIM_ComputerSystem whose Dedicated property
 contains a value of 29 (Chassis Manager).

581 **9.6 Find All Power Domains for the Modular System**

- 582 A client can find all of the power domains for the modular system as follows:
- 5831)Find instances of CIM_AdminDomain that are associated with the Central Instance through an584instance of CIM_SystemComponent whose PartComponent property references the585CIM_AdminDomain instance.
- 586 2) For each instance of CIM_AdminDomain, determine if the ElementName property matches
 587 "Power Domain".

588 9.7 Determine the Power Supply for a Component

589 When a component is modeled with an instance of a subclass of CIM_ManagedSystemElement, a client 590 can determine the power supply for a component by using the following steps. Note that the algorithm 591 terminates after steps 1, 2, 3, and 4.

- Query for an instance of CIM_SuppliesPower that references the CIM_ManagedSystemElement
 instance.
- 5941.1If one or more such instances exist, the associated instances of CIM_PowerSupply supply595power to the CIM_ManagedSystemElement instance.
- 2. Query for an instance of CIM_SystemComponent that references theCIM_ManagedSystemElement instance.
- 5982.1If the GroupComponent reference is to an instance of CIM_AdminDomain, query for an
instance of CIM_SuppliesPower that references the CIM_AdminDomain instance.
- If one or more such instances exist, the associated instances of CIM_PowerSupply supply
 power to the CIM_ManagedSystemElement instance.
- 3. Query for an instance of CIM_SystemComponent (or a subclass) in which the
 CIM_ManagedSystemElement instance is the value of the PartComponent reference and an
 instance of CIM_ComputerSystem is the value of the GroupComponent reference.
 - 3.1 Find all instances of CIM_PowerSupply that are associated with the CIM_ComputerSystem instance through the CIM_SystemDevice association.
- 6073.2If one or more such instances exist, the associated instances of CIM_PowerSupply supply608power to the CIM_ManagedSystemElement instance.
- 4. If the instance of CIM_ManagedSystemElement is an instance of CIM_Slot, complete the following steps:
- 6114.1Follow the CIM_Container or CIM_PackageInSlot associations to an instance of612CIM_PhysicalElement that represents an outer container.
- 6134.1.1If the instance of CIM_PhysicalElement is an instance of CIM_PhysicalPackage or a614subclass, query for an instance of CIM_ComputerSystemPackage that references the615CIM_PhysicalPackage instance. If not, repeat step 4.1.
 - 4.1.2 If such an instance exists, select the CIM_ComputerSystem instance and proceed to step 4.2. If not, repeat step 4.1.
- Find all instances of CIM_PowerSupply that are associated with the CIM_ComputerSystem
 instance through the CIM_SystemDevice association.
- 4.3 If one or more such instances exist, the associated instances of CIM_PowerSupply supply
 bower to the CIM_ManagedSystemElement instance.

622 **9.8 Find All Cooling Domains for the Modular System**

- A client can find all of the cooling domains for the modular system as follows:
- Find instances of CIM_AdminDomain that are associated with the Central Instance through an
 instance of CIM_SystemComponent whose PartComponent property references the
 CIM_AdminDomain instance.
- 627 2) For each instance of CIM_AdminDomain, determine if the ElementName property matches 628 "Cooling Domain".

605

606

629 9.9 Determine the Fan for a Component

630 When a component is modeled with an instance of a subclass of CIM_ManagedSystemElement, a client 631 can determine the fan for a component by using the following steps. Note that the algorithm terminates 632 after steps 1, 2, 3, and 4.

633 1. 634	Query for an instance of CIM_AssociatedCooling that references the CIM_ManagedSystemElement instance.					
635 636	1.1 If one or more such instances exist, the associated instances of CIM_Fan provide cooling to the CIM_ManagedSystemElement.					
637 2. 638	Query for an instance of CIM_SystemComponent that references the CIM_ManagedSystemElement instance.					
639 640	2.1 If the GroupComponent reference is to an instance of CIM_AdminDomain, query for an instance of CIM_AssociatedCooling that references the CIM_AdminDomain instance.					
641 642	2.2 If one or more such instances exist, the associated instances of CIM_Fan provide cooling to the CIM_ManagedSystemElement.	I				
643 3. 644 645	Query for an instance of CIM_SystemComponent (or a subclass) in which the CIM_ManagedSystemElement instance is the value of the PartComponent reference and an nstance of CIM_ComputerSystem is the value of the GroupComponent reference.					
646 647	Find all instances of CIM_Fan that are associated with the CIM_ComputerSystem instance through the CIM_SystemDevice association.					
648 649	If one or more such instances exist, the associated instances of CIM_Fan provide cooling to the CIM_ManagedSystemElement.					
650 4. 651	If the instance of CIM_ManagedSystemElement is an instance of CIM_Slot, complete the following steps:					
652 653	4.1 Follow the CIM_Container or CIM_PackageInSlot associations to an instance of CIM_PhysicalElement that represents an outer container.					
654 655 656	4.1.1 If the instance of CIM_PhysicalElement is an instance of CIM_PhysicalPackage or a subclass, query for an instance of CIM_ComputerSystemPackage that references th CIM_PhysicalPackage instance. If not, repeat step 4.1.					
657 658	4.1.1.1 If such an instance exists, select the CIM_ComputerSystem instance and proceed to step 4.2. If not, repeat step 4.1.					
659 660	4.2 Find all instances of CIM_Fan that are associated with the CIM_ComputerSystem instance through the CIM_SystemDevice association.					
661 662	4.3 If one or more such instances exist, the associated instances of CIM_Fan provide cooling to the CIM_ManagedSystemElement instance.	I				

663 **10 CIM Elements**

Table 4 shows the instances of CIM Elements for this profile. Instances of the CIM Elements shall be
 implemented as described in Table 4. Sections 7 ("Implementation") and 8 ("Methods") may impose
 additional requirements on these elements.

667

Table 4 – Required CIM Elements: Modular System Profile

Element Name	Requirement	Description
Classes		
CIM_AdminDomain	Optional	See 10.1 and 10.2.
CIM_Chassis	Mandatory	See 10.3.
CIM_ComputerSystem	Mandatory	See 10.4.
CIM_ComputerSystemPackage	Mandatory	See 10.5.
CIM_ConcreteDependency	Conditional	See 7.3.1.4 and 10.6.
CIM_PhysicalPackage	Conditional	See 10.7 and 7.3.1.
CIM_RegisteredProfile	Mandatory	See 10.8.
CIM_SystemComponent	Conditional	See 10.9, 10.10, 10.11, and 10.12.
Indications		
None defined in this profile		

668 **10.1 CIM_AdminDomain—Power Domain**

669 CIM_AdminDomain represents power domains of the modular system. Table 5 contains the requirements 670 for properties of the instance.

671

Table 5 – Class: CIM_AdminDomain – Power Domain

Elements	Requirement	Notes
Name	Mandatory	None
CreationClassName	Mandatory	None
ElementName	Mandatory	Matches "Power Domain"

672 **10.2 CIM_AdminDomain—Cooling Domain**

- 673 CIM_AdminDomain represents cooling domains of the modular system. Table 6 contains the
- 674 requirements for properties of the instance.

675

Table 6 – Class: CIM_AdminDomain – Cooling Domain

Elements	Requirement	Notes
Name	Mandatory	None
CreationClassName	Mandatory	None
ElementName	Mandatory	Matches "Cooling Domain"

676 **10.3 CIM_Chassis**

- 677 CIM_Chassis is defined by the *Physical Asset Profile*. The requirements denoted in Table 7 are in
- 678 addition to those mandated by the *Physical Asset Profile*.
- 679

Table 7 – Class: CIM_Chassis

Elements	Requirement	Notes
MultipleSystemSupport	Mandatory	This property shall have a value of TRUE.

680 **10.4 CIM_ComputerSystem**

681 An instance of CIM_ComputerSystem represents the modular enclosure. Table 8 contains the 682 requirements for properties of the instance.

683

Table 8 – Class: CIM_ComputerSystem

Elements	Requirement	Notes
Dedicated	Mandatory	Matches 0 (Other)
OtherDedicatedDescriptions	Mandatory	Matches "Modular"
Name	Mandatory	None
CreationClassName	Mandatory	None
ElementName	Mandatory	Pattern (".*")
OperationalStatus	Mandatory	None
HealthState	Mandatory	None

684 **10.5 CIM_ComputerSystemPackage**

685 CIM_ComputerSystemPackage associates the CIM_Chassis instance for the modular enclosure with the 686 CIM_ComputerSystem instance for the modular enclosure. Requirements specified in Table 9 are in 687 addition to those specified in the *Physical Asset Profile*.

688

Table 9 – Class: CIM_ComputerSystemPackage

Elements	Requirement	Notes
Antecedent	Mandatory	This property shall be a reference to an instance of CIM_Chassis that represents the modular enclosure.
		Cardinality 1
Dependent	Mandatory	This property shall be a reference to the Central Instance.
		Cardinality 1

10.6 CIM ConcreteDependency 689

- 690 CIM ConcreteDependency associates a blade expansion physical package with a blade physical
- package. Table 10 contains the requirements for properties of the instance. 691
- 692

Table 10 – Class: CIM_ConcreteDependency

Elements	Requirement	Notes
Antecedent	Mandatory	This property shall be a reference to an instance of CIM_PhysicalPackage that represents the blade.
		Cardinality 1
Dependent	Mandatory	This property shall be a reference to an instance of CIM_PhysicalPackage that represents the blade expansion.
		Cardinality *

693 10.7 CIM_PhysicalPackage

694 CIM_PhysicalPackage is defined by the *Physical Asset Profile*. The requirements denoted in Table 11 are in addition to those mandated by the Physical Asset Profile. 695

696

Table 11 – Class: CIM PhysicalPackage

Elements	Requirement	Notes
PackageType	Mandatory	See 7.3.1.

10.8 CIM RegisteredProfile 697

698 CIM_RegisteredProfile identifies the Modular System Profile in order for a client to determine whether an instance of CIM_ComputerSystem is conformant with this profile. CIM_RegisteredProfile is defined by the 699 Profile Registration Profile. With the exception of the mandatory values specified for the properties in 700 Table 12, the behavior of the CIM RegisteredProfile instance is in accordance with the Profile 701

Registration Profile. 702

703

Table 12 – Class: CIM RegisteredProfile

Elements	Requirement	Notes
RegisteredName	Mandatory	This property shall have a value of Modular System.
RegisteredVersion	Mandatory	This property shall have a value of "1.0.0".
RegisteredOrganization	Mandatory	This property shall have a value of 2 (DMTF).

704 NOTE: Previous versions of this document included the suffix "Profile" for the RegisteredName value. If

705 implementations querying for the RegisteredName value find the suffix "Profile", they should ignore the suffix, with

706 any surrounding white spaces, before any comparison is done with the value as specified in this document.

707 **10.9 CIM_SystemComponent—Cooling Domains**

708 CIM_SystemComponent associates an instance of a sub-class of CIM_ManagedElement with an

instance of CIM_AdminDomain representing the cooling domain in which the element is installed. If no

cooling domains are modeled, or no elements that receive cooling are modeled, no instances of

711 CIM_SystemComponent exist. Table 13 contains the requirements for properties of the instance. The

existence of CIM_SystemComponent in this context is conditional on the modeling of an element installed

713 in the cooling domain.

714

Table 13 – Class: CIM_SystemComponent – Cooling Domains

Elements	Requirement	Notes
GroupComponent	Mandatory	See 7.8.
PartComponent	Mandatory	See 7.8.

715 **10.10 CIM_SystemComponent—Power Domains**

716 CIM_SystemComponent associates an instance of a sub-class of CIM_ManagedElement with an

instance of CIM_AdminDomain representing the power domain in which the element is installed. If no

power domains are modeled, or no elements that receive power are modeled, no instances of

719 CIM_SystemComponent exist. Table 14 contains the requirements for properties of the instance. The

existence of CIM_SystemComponent in this context is conditional on the modeling of an element installed

in the power domain.

722

Table 14 – Class: CIM_SystemComponent – Power Domains

Elements	Requirement	Notes
GroupComponent	Mandatory	See 7.6.
PartComponent	Mandatory	See 7.6.

723 **10.11 CIM_SystemComponent—Chassis Manager**

724 CIM_SystemComponent associates the CIM_ComputerSystem instance that represents a chassis

725 manager with the CIM_ComputerSystem instance that represents the modular enclosure in which the

726 chassis manager is installed. If no chassis managers are modeled, no instances of

727 CIM_SystemComponent exist. Table 15 contains the requirements for properties of the instance. The

existence of CIM_SystemComponent in this context is conditional on the modeling of a chassis manager.

729

Table 15 – Class: CIM_SystemComponent – Chassis Manager

Elements	Requirement	Notes
GroupComponent	Mandatory	See 7.4.
PartComponent	Mandatory	See 7.4.

730 **10.12 CIM_SystemComponent—Processor Blades**

731 CIM_SystemComponent associates the CIM_ComputerSystem instance that represents a processor

blade with the CIM_ComputerSystem instance that represents the modular enclosure in which the

733 processor blade is installed. If no processor blades are modeled, no instances of CIM_SystemComponent

exist. Table 16 contains the requirements for properties of the instance. The existence of

735 CIM_SystemComponent in this context is conditional on the modeling of a processor blade.

736

Table 16 – Class: CIM_SystemComponent – Processor Blades

Elements	Requirement	Notes
GroupComponent	Mandatory	See 7.3.
PartComponent	Mandatory	See 7.3.

ANNEX A (informative)

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742

743

Change Log

Version	Date	Description
1.0.0	06-17-2009	DMTF Standard Release